

HSTL Clock Buffer Using the CDCV850

Falk Alicke

TI Clock Solutions, Communication and Control Products

ABSTRACT

The demand for driving 1.5-V HSTL signals for high-integrated and low-voltage digital logic is increasing. Most current systems use LVDS, LVPECL, or 2.5-V LVCMOS signaling levels. Therefore, a solution is needed to convert these clock signals into HSTL signal swing.

The purpose this report is to show how to generate an HSTL compliant clock signal using the CDCV850. This clock buffer accepts LVDS, LVPECL, SSTL2, or 2.5-V LVCMOS signals on its input.

The CDCV850 runs from a power supply of 2.5 V. A few additional resistors and capacitors are required to shift the voltage level to HSTL and provide the correct attenuation factor to the CDCV850 output to meet HSTL signal swing.

HSTL Specification

The HSTL specification EIA/JESD8-6 (August 1995) and JESD8-11 (October 2000) has been used as reference.

CDCV850 Output Compliance to HSTL Specification

After comparing the CDCV850 device output specification with the HSTL output requirement, it has been determined that an attenuation factor of 1.4 ensures the CDCV850 output to be fully compliant with HSTL output specifications. In addition, the output signal must be ac-coupled to shift the common mode voltage to V_{ref} of the HSTL input buffer (typically 750 mV). The drawings below show a complete interface circuit to provide signal attenuation and level shifting.

Two cases are shown, one for signal termination at the line end and another for serial transmission line termination. The termination of the signal at the HSTL input stage is the better approach to assure minimal signal reflections and best possible jitter performance. However, if the application demands serial termination because board space is limited at the HSTL input buffer, drawing (c) shows a solution to the problem. The transmitter side is impedance matched to $50\ \Omega$ and ensures proper line termination.

CDCV850 Input

The CDCV850 provides internal ac-coupling of the inputs. Therefore, the CDCV850 can handle a wide range of differential input signals as LVDS, LVPECL, or SSTL2. In addition, the user can drive the CDCV850 by a single ended signal like 2.5-V LVCMOS. In this case, it is recommended to tie the second input directly to GND when using the CDCV850 in PLL mode or tie it to $V_{cc}/2$ when used in buffered mode ($AVDD=GND$).

Calculations and Support

For the calculations of how these resistor values have been derived please contact the TI clock distribution team (f-alicke@ti.com or kalmustafa@ti.com). Also, there are additional clock drivers from TI available to support HSTL signaling levels. If your HSTL clock input is only single ended, TI can provide further assistance.

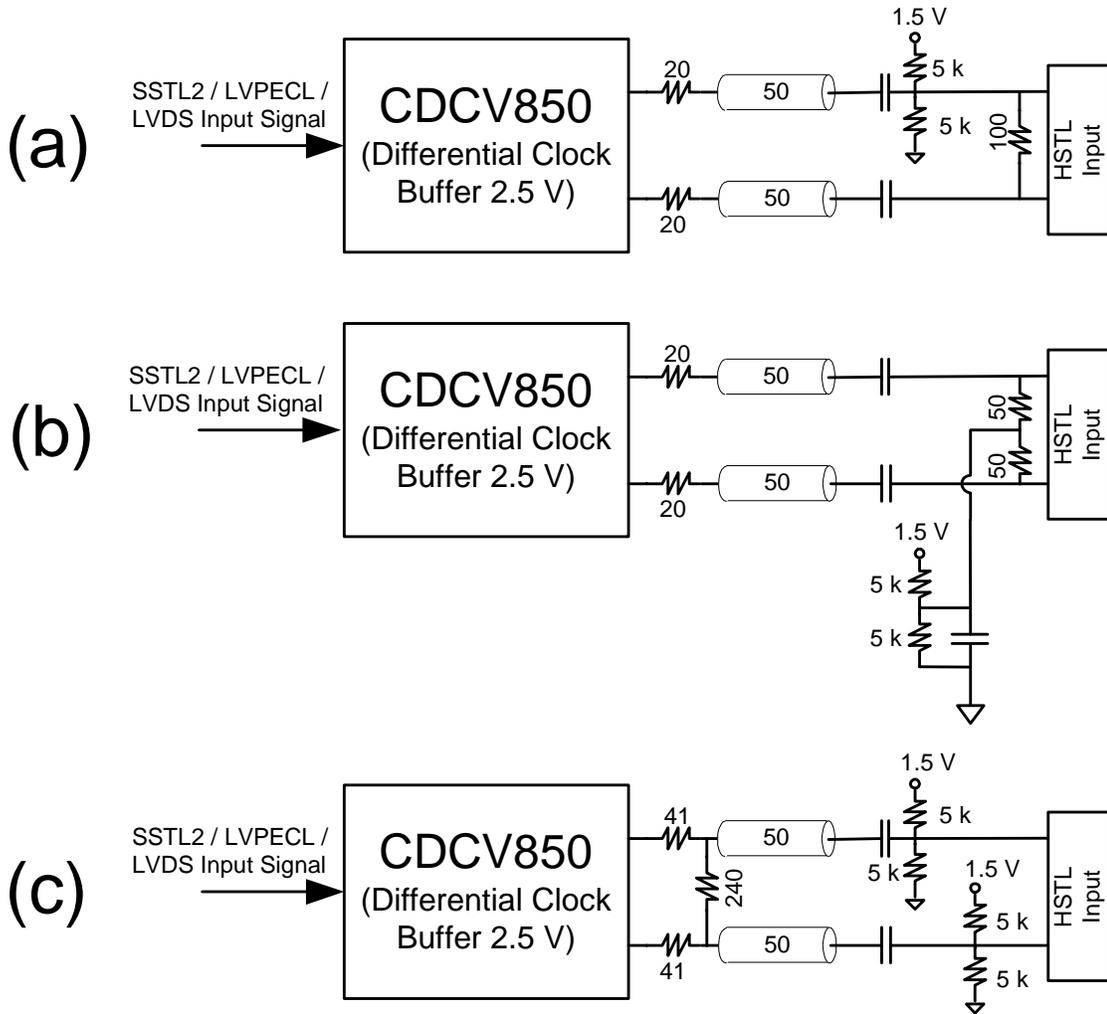


Figure (a): HSTL signal generation with line termination at the receiver; the transmitter stage has a combined output impedance of $\sim 65\ \Omega$ ($45R+20R$)
Figure (b): Same as Figure (a) but with an improved receiver termination network to properly terminate any odd-mode noise (noise that couples into only one transmission line or transmitter differential signal mismatch)
Figure (c): HSTL signal generation with serial transmission line termination; combined output impedance is matched to $50\ \Omega$ ($45+41||120$)

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265